

## Silicon Carbide Power MOSFET

### N-Channel Enhancement Mode

#### Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Easy to Parallel and Simple to Drive
- Avalanche Ruggedness
- Halogen Free, RoHS Compliant

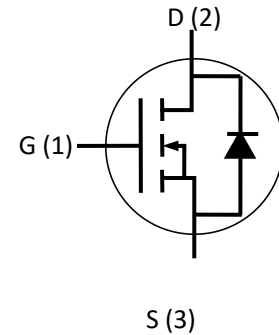
#### Benefits

- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency

#### Applications

- Solar Inverters
- Switch Mode Power Supplies
- High Voltage DC/DC Converters
- Battery Chargers
- Motor Drives
- Pulsed Power applications

#### Package



Part Number	Package
JX3S0060R065T3	TO-263-3

#### Maximum Ratings ( $T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{DSmax}$	Drain - Source Voltage	650	V	$V_{GS}=0V, I_D=100\mu A$	
$V_{GSmax}$	Gate - Source Voltage	-10/+25	V	Absolute maximum values	
$V_{GSop}$	Gate - Source Voltage	-5/+20	V	Recommended operational values	
$I_D$	Continuous Drain Current	30	A	$V_{GS}=20V, T_C=25^\circ\text{C}$	
		22		$V_{GS}=20V, T_C=100^\circ\text{C}$	
$I_{DM}$	Pulse Drain Current	65	A	Pulse width limited by $T_{jmax}$	
$P_D$	Power Dissipation	171	W	$T_C=25^\circ\text{C}, T_J=150^\circ\text{C}$	Fig. 10
$T_J, T_{stg}$	Operating Junction and Storage Temperature	-55 to +150	$^\circ\text{C}$		

**Electrical Characteristics**

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650			V	$V_{GS}=0V, I_D=100\mu A$	
$V_{GS(th)}$	Gate Threshold Voltage	2.0	2.40	4.0	V	$V_{GS}=V_{DS}, I_{DS}=5mA, T_C=25^\circ C$	Fig. 6
			1.8			$V_{GS}=V_{DS}, I_{DS}=5mA, T_C=150^\circ C$	
$I_{DSS}$	Zero Gate Voltage Drain Current		2	100	$\mu A$	$V_{DS}=650V, V_{GS}=0V$	
$I_{GSS}$	Gate-Source Leakage Current		50	200	nA	$V_{GS}=20V, V_{DS}=0V$	
$R_{DS(on)}$	Drain-Source on-state Resistance		60	80	m $\Omega$	$V_{GS}=20V, I_D=20A, T_C=25^\circ C$	Fig. 4
			95			$V_{GS}=20V, I_D=20A, T_C=175^\circ C$	
$g_{fs}$	Transconductance		4.7		S	$V_{GS}=20V, I_D=20A, T_J=25^\circ C$	Fig. 5
			5.9			$V_{GS}=20V, I_D=20A, T_J=175^\circ C$	
$C_{iss}$	Input Capacitance		1700		pF	$V_{GS}=0V, V_{DS}=1000V, f=1MHz$ $V_{AC}=25mV$	Fig. 8
$C_{oss}$	Output Capacitance		172				
$C_{rss}$	Reverse Transfer Capacitance		77				
$E_{ON}$	Turn-On Switching Energy		140		$\mu J$	$V_{DS}=400V, V_{GS}=-5/20V, I_D=10A,$ $R_{G(ext)}=5\Omega, L=142\mu H$	
$E_{OFF}$	Turn-Off Switching Energy		32				
$t_{d(on)}$	Turn-On Delay Time		15		ns	$V_{DD}=400V, V_{GS}=-0/20V$ $I_D=10A, R_{G(ext)}=5\Omega,$ $R_L=40\Omega, \text{Timing relative to VDS}$	
$t_r$	Rise Time		45				
$t_{d(off)}$	Turn-Off Delay Time		13				
$t_f$	Fall Time		10				
$R_{G(int)}$	Internal Gate Resistance		2.0		$\Omega$	$f=1MHz, V_{AC}=25mV$	
$Q_{gs}$	Gate to Source Charge		18		nC	$V_{DD}=400V, V_{GS}=-0/20V$ $I_D=10A$	Fig. 9
$Q_{gd}$	Gate to Drain Charge		19				
$Q_g$	Total Gate Charge		65				

**Reverse Diode Characteristics**

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_{SD}$	Diode Forward Voltage	3.5		V	$V_{GS}=-5V, I_{SD}=10A, T_J=25^\circ C$	Fig. 7
		3.3		V	$V_{GS}=-5V, I_{SD}=10A, T_J=175^\circ C$	
$I_S$	Continuous Diode Forward Current	20		A	$T_C=25^\circ C$	
$t_{rr}$	Reverse Recovery time	37		ns	$V_{GS}=-5V, I_{SD}=20A, V_R=400V,$ $dif/dt=1000A/\mu s;$	
$Q_{rr}$	Reverse Recovery Charge	198		nC		
$I_{rrm}$	Peak Reverse Recovery Current	12		A		

**Thermal Characteristics**

Symbol	Parameter	Typ.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.73	$^\circ C/W$		Fig. 11
$R_{\theta JA}$	Thermal Resistance From Junction to Ambient	35			

## Typical Performance

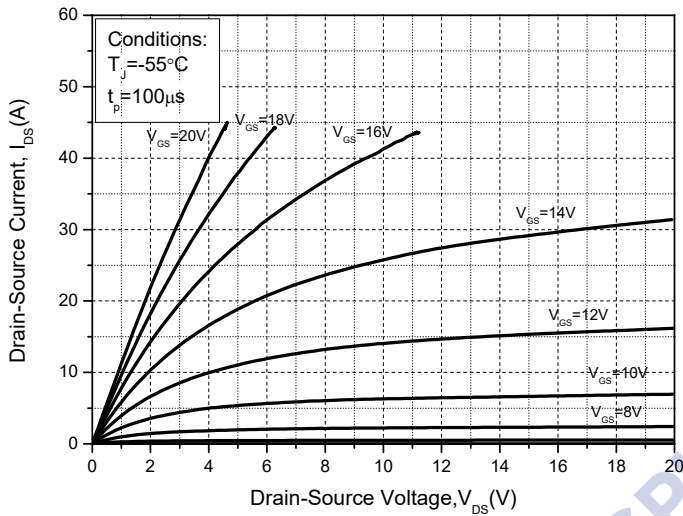


Figure 1. Output Characteristics  $T_J = -40^\circ\text{C}$

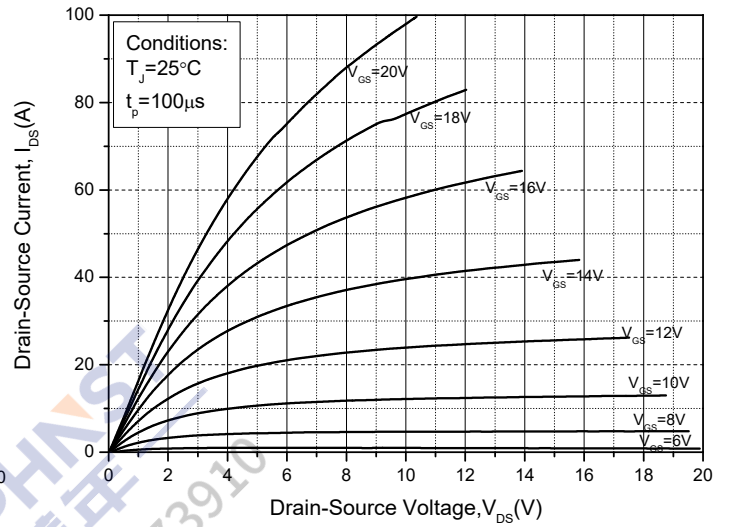


Figure 2. Output Characteristics  $T_J = 25^\circ\text{C}$

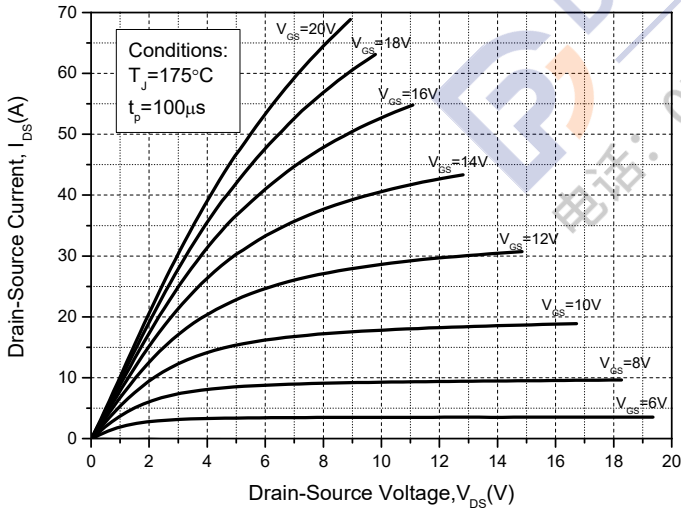


Figure 3. Output Characteristics  $T_J = 175^\circ\text{C}$

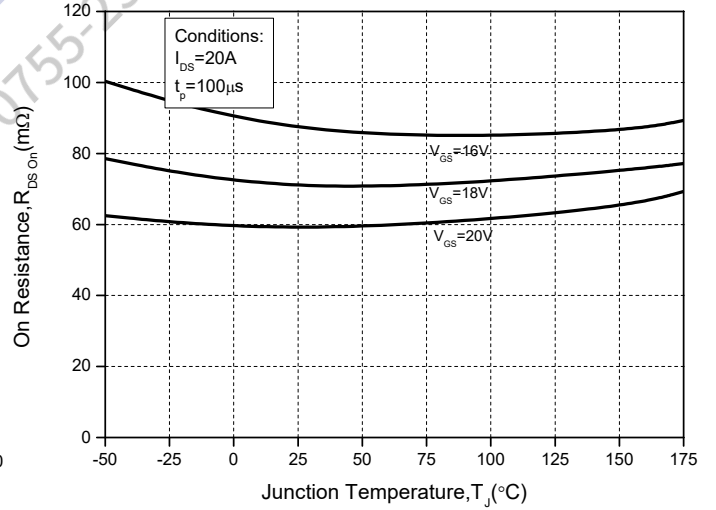


Figure 4. On-Resistance For Various Gate Voltage

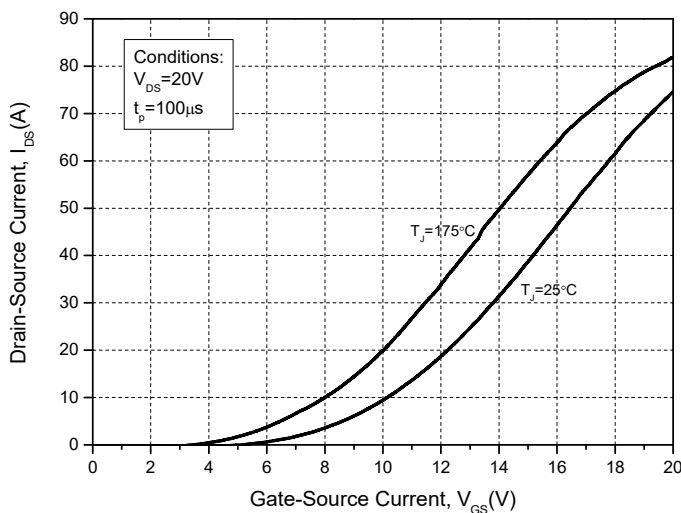


Figure 5. Transfer Characteristic For Various Junction Temperatures

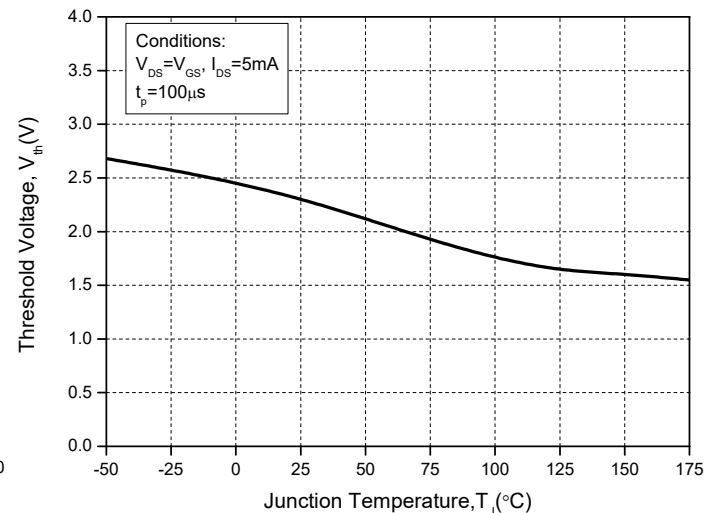


Figure 6. Threshold Voltage vs. Temperature

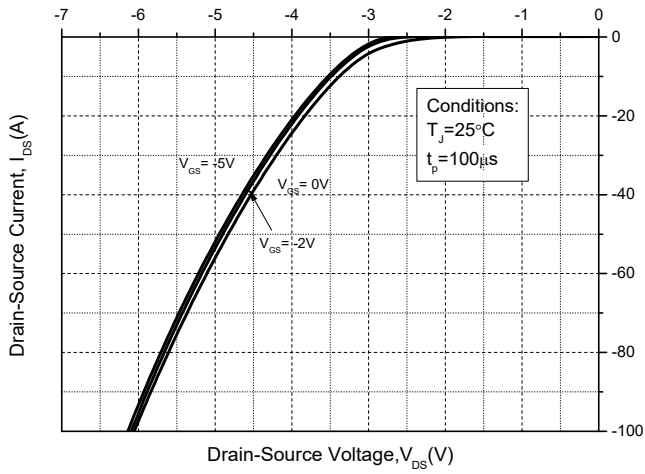


Figure 7. Body Diode Characteristics

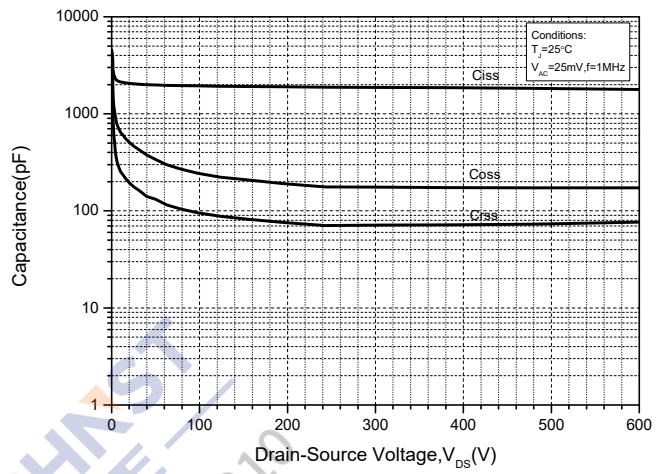


Figure 8. Capacitances vs. Drain-Source Voltage

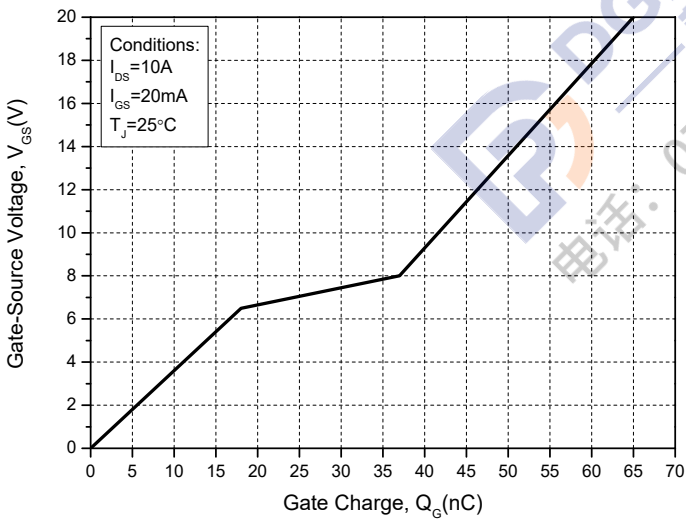


Figure 9. Gate Charge Characteristics

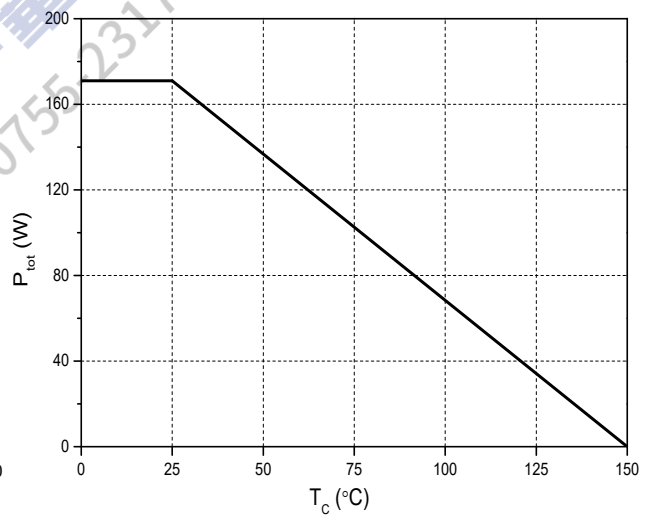


Figure 10. Power Dissipation Derating

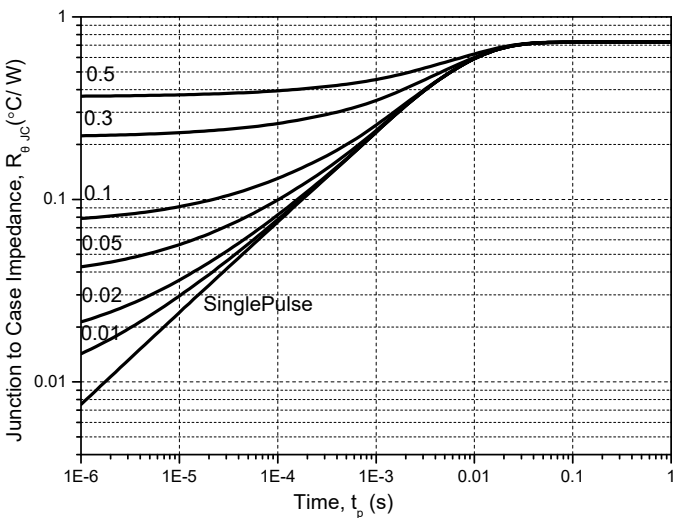
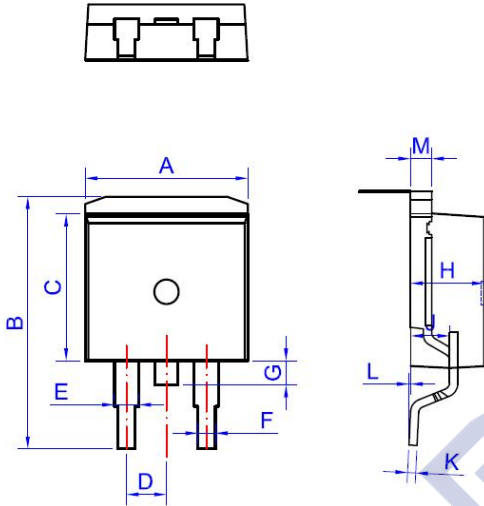


Figure 11. Transient Thermal Impedance

Package Dimensions: TO-263-3



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
H	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
M	1.25		1.35	0.049		0.053

DGP  
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